OUTLINE NUMBER TI	ITLE	ISSUE LETTER	DATE	
Design Guide 4.1	Unused			
Design Guide 4.2	General Requirements	В	December 2008	
Design Guide 4.3	Unused			
Design Guide 4.4	English Bumpered Gullwing Quad Flat Package (PQFP)	А		
Design Registration 4.5	Ball Grid Array and Interstitial Ball Grid Array Package (BGA) and (IBGA)	N.01	November 2018	
Design Guide 4.6	Fine Pitch Rectangular Ball Grid Array Package (FRBGA)	D.01	July 2012	
Design Guide 4.7	Die-Size Ball Grid Array Package (DSBGA)	E.01	May 2010	
Design Guide 4.8	Plastic Quad and Dual Inline Square and Rectangular No Lead Packages (With Optional Thermal Enhancements) (QFN/SON)	C	September 2006	
Design Guide 4.9	Generic Matrix Tray for Handling and Shipping (Low Stacking Profile for BGA Packages)	А	April 2000	
Design Guide 4.10	Generic Matrix Tray for Handling and Shipping	D	October 2002	
Design Guide 4.11	Dual Inline Plastic Family	А	July 1994	
Design Guide 4.12	To Be Determined			
Design Guide 4.13	Metric Small Outline J-Leaded Package (SOJ)	А	August 1996	
Design Guide 4.14	Ball Grid Array Package (BGA)	J.01	February 2019	
Design Guide 4.15	Metric Thin Small Outline Package Type II (TSOPII)	В	May 2004	
Design Guide 4.16	Ultra-Thin Plastic No Lead Small Outline Package (UR-PDSO-N)	А	February 1998	
Design Guide 4.17	Ball Grid Array (BGA) Package Measurement and Methodology	С	July 2008	
Design Guide 4.18	Wafer Level BGA (WLBGA)	A.01	April 2021	
Design Guide 4.19	Quad No-Lead Staggered and Inline Multi-Row Packages (With Optional Thermal Enhancements) (QFN)	D	May 2007	
Design Guide 4.20	Small Scale Plastic Quad and Dual Inline Square and Rectangular No-Lead Packages (With Optional Thermal Enhancements) (QFN/SON)	F	September 2016	
Design Guide 4.21	Internal Stacking Module, Land Grid Array Packages with External Interconnect Terminals (ISM)	А	March 2007	
Design Guide 4.22	Fine-Pitch Square Ball Grid Array Package (FBGA) Package on Package (PoP)	D	April 2010	
Design Guide 4.23	Punch-Singulated Fine Pitch Square Very Thin and Very-Very Thin Profile Leadframe-Based Quad No-Lead Staggered Dual-Row Packages (With Optional Thermal Enhancements (QFN)	A	November 2005	

OUTLINE NUMBER T	ITLE	ISSUE LETTER	DATE
Design Cuide 4.24	Saalahla Ound Elat Na Land Daalaa aas Saunaa	D	August 2016
Design Guide 4.24	and Rectangular (Scalable QFN)	В	August 2016
Design Registration 4.25	Fine-Pitch Land Grid Array Package Square and	В	August 2016
	Rectangular (FLGA, FRLGA)		
Design Registration 4.26	Micropillar Grid Array	В	November 2015
Design Registration 4.27	BGA Package (BGA)	F.01	November 2018

OUTLINE		ISSUE	
NUMBER	TITLE	LETTER	DATE
SPP-001	SPP Document Procedures		March 1991
SPP-002	Pin #1 Mark Function and Location		June 1991
SPP-003	Metrication		July 1991
SPP-004	Lead Finish and Base Metal Specification		June 1991
SPP-005	Pin #1 Orientation for TAB Packages		June 1991
SPP-006	Definition of DAMBAR Protrusion and Intrusion		June 1991
SPP-007	Use of "Proposed" on Ballots		June 1991
SPP-008	Gull-wing Lead Dimensioning		September 1991
SPP-009	Inclusion of Nominal Dimensions		September 1991
SPP-010	Grid Array Terminal Position Numbering		September 1991
SPP-011	J Lead Dimensioning of Lead Contact Points		January 1992
SPP-012	Pin #1 Mark and Lead Numbering Convention for		January 1993
	Dual-In-Line Packages with Standard and Reverse-		
	Bend Lead Form		
SPP-013	Registered and Standard Outlines	А	October 2014
SPP-014	Mold Flash Interlead Flash Gate Burrs and		April 1994
	Protrusions for Plastic Packages		
SPP-015	Requirements for Applying Material and Finish		May 1995
	Specifications to Selected Mechanical Outlines		
SPP-016	Inactivation and Rescission		
SPP-017	Standard Overall Profile Height Codes for Packages	С	November 2004
SPP-018	Procedure for Making Editorial Corrections to		May 1999
	Published Documents		
SPP-019	Measuring Stand-Off Heights of Packages	A	June 2001
SPP-020	Rectangular Grid Array Terminal Position Numbering	Α	July 2003
SPP-021	JC-11 Change Record Methodology	А	December 2005
SPP-022	Package Thermal Pad Requirements	А	October 2005
SPP-023	Module Insertion Procedure for DIMM and	В	February 2013
	miniDIMM Connectors		
SPP-024	Reflow Flatness Requirements for Ball Grid Array	A	March 2009
SPP-025	Package Variation Designators	С	August 2018

OUTLINE		ISSUE	
NUMBER	TITLE	LETTER	DATE
CS-001	Metric Tab Magazine Family	В	March 1996
CS-002	Thin Matrix Tray for Handling/Shipping of PQFP	А	March 1993
CS-003	Thin Matrix Tray for Handling and Shipping of	В	April 1993
	PLCC Packages		
CS-004	FQFP/MQFP Thin Matrix Tray for Handling and	В	May1996
	Shipping		
CS-005	Thin Matrix Tray for Handling/Shipping of TSOP	В	November 1998
	(II)		
CS-006	Metric Tab Tape Carrier Family	А	November 1993
CS-007	LQFP/TQFP Thin Matrix Tray for Handing and	А	May 1996
	Shipping		
CS-008	TSOP I Thin Matrix Tray for Shipping and Handling	А	March 1996

OUTLINE		ISSUE	
NUMBER	TITLE	LETTER	DATE
GS-001	Gauge for Header Family		June 1961
GS-002	Gauge for Header Family		September 1962
GS-003 AA-BD	Dual In-Line Gauge	С	March 1993
GS-004	FBDIMM Socket Insertion and Extraction Gauge	А	July 2006
GS-005	DDR3 DIMM Socket Insertion and Extraction	А	July 2006
	Gauge		
GS-006	SMT DDR2 DIMM Socket Coplanarity	А	June 2007
	Measurement Gauge		
GS-007	DDR2 DIMM Socket Insertion and Extraction Force	А	June 2007
	Gauge		
GS-008	DDR3 DIMM Connector Insertion Force Gauge	А	October 2007
GS-009	SMT DDR3 DIMM Socket Coplanarity	А	January 2009
	Measurement Gauge		
GS-010	DDR4 DIMM Socket Insertion and Extraction Force	С	November 2017
	Gauge		

OUTLINE		ISSUE	
NUMBER	TITLE	LETTER	DATE
MS-001	R-PDIP-T Dual Inline Plastic Family .300" Row Spacing	D	June 1993
MS-002	Leadless Chip Carrier .050" Type A	А	September 1980
MS-003	Leadless Chip Carrier .050" Type B	А	September 1980
MS-004	Leadless Chip Carrier .050" Type C	В	May 1990
MS-005	Leadless Chip Carrier .050" Type D	А	September 1980
MS-006	Leaded Chip Carrier .050" Type A	А	September 1980
MS-007	Leaded Chip Carrier .050" Type A	А	September 1980
MS-008	Leaded Chip Carrier .050" Type B	А	September 1980
MS-009	Leadless Chip Carrier .040"	А	September 1980
MS-010	Dual Inline Plastic Family (R-PDIP-T) .400" Row	С	November 1993
	Spacing		
MS-011	Standard Dual in Line Family .600" Row Spacing (Plastic)	В	June 1988
MS-012	Small Outline (SO) Family Peripheral Terminals 3.75 (.150") Body Width (Plastic)	G.02	September 2020
MS-013	Small Outline (SO) Family Peripheral Terminals 7 50 (300") Body Width (Plastic)	G	November 2020
MS-014	Single Laver Chip Carrier .040"	А	August 1985
MS-015	Side Brazed Ceramic Dual in Line .300"900"	А	July 1990
	Spacing (.100 center)		
MS-016	Plastic chip Carrier Rect050"	А	December 1989
MS-017	Ceramic Pin Grid Array Package Family, S-C-GA	В	June 1993
	(.100" Pitch, Cavity Down)		
MS-018	Square Plastic Chip Carrier Family .050" Lead Pitch (S-POCC-J)	А	June 1993
MS-019	R-PDIP-T Dual in-line (Shrink .070") Plastic Family .300" Row Spacing	В	March 1993
MS-020	R-PDIP-T Dual in-line (Shrink .070") Plastic Family .600" Row Spacing	В	March 1993
MS-021	R-PDIP-T Dual in-line (Shrink .070") Plastic Family 750" Row Spacing	А	March 1993
MS-022	Metric Plastic Quad Flat Pack Family 1.0, 0.8, 0.65 Pitch	В	December 1996
MS-023	Plastic Small Outline J-Lead Package, .300" Wide Body050" Pitch (R-PDSO-J/SOJ)	А	March 1995
MS-024	Thin Small Outline Package 10.16mm Body Family	Н	June 2006
MS-025 AA-BD	Thin Small Outline Package, 7.62 mm Body Family	В	December 1999
MS 026	(R-PDSO-G/TSOP II) Low/Thin Profile Plastic Quad Elat Package 2.00	D	January 2001
WIS-020	mm Footprint, Optional Heat Slug	U	January 2001

OUTLINE		ISSUE	
NUMBER	TITLE	LETTER	DATE
MS-027	PDSO-J	А	June 1995
MS-028	Rectangular Plastic Ball Grid Array 1.27 mm Pitch	С	May 2000
MS-029	Fine Pitch Plastic Quad Flat Package Outline 2.6 mm Footprint	А	August 1997
MS-030	Ceramic Dual-in-Line (DIP) Family, .300" Row Spacing	А	May 1999
MS-031	Ceramic Dual-in-Line (DIP) Family, .400" Row Spacing	А	May 1999
MS-032	Ceramic Dual-in-Line (DIP) Family, .600" Row Spacing	А	May 1999
MS-033	Ceramic Dual Flatpack Family, .050" Pitch	А	July 1999
MS-034	Plastic Square Ball Grid Array Family	G	January 2017

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
PS-003	DDR4 260 Pin SODIMM Connector	A.01	July 2016
PS-004	UFS Card 6Gb/s UFS Card Socket	А	July 2020
PS-005	DDR5 288 Pin U/R/LR DIMM Connector	А	January 2021
	Performance Standard, DDR5		·

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
TS-001	Plastic Single-in-Line Flange-Mounted	А	August 1989
TS-002	Header Family Insertion Mount (Peripheral	А	June 1995
	Terminals)		
TS-003	Header Family Surface Mounted (Peripheral	В	June 1997
	Terminals)		
TS-004	Flange-Mounted Header Family	А	June 1995
TS-005	Surface-Mounted Header Family	А	June 1995

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
US-001	Tape Automated Bonding (TAB) Package Family	В	November 1993

OUTLINE		ISSUE	
NUMBER	TITLE	LETTER	DATE
CO-001	Magazine Family DIP 7.62 mm Row Spacing	В	May 1978
CO-002	TO-220 Magazine	B	May 1978
CO-003	Magazine Family DIP 7.62 mm Row Spacing	B	May 1978
CO-004	Square Magazine for DIP	B	May 1978
CO-005	Magazine for DIP 7.62, 10.16, 15.24 mm	Ā	May 1979
CO-006	Magazine for 68-Pin Chip Carrier	А	November 1982
CO-007	Pin Grid Array Pkg., .100" Centers	А	October 1987
CO-008	Fine Pitch Plastic Shipping Tube Family	А	July 1988
CO-009	Tab Tape Carrier 35, 48, 70 mm	А	July 1989
CO-010	Tray for Handling and Shipping of PGA Packages	Е	November 1994
CO-011	Tray for Handling and Shipping of CQFP Packages	В	November 1992
CO-012	EIAJ- Tray for Handling and Shipping of Metric	С	November 1992
	QFP Packages		
CO-013	Generic Carrier Family	В	January 1993
CO-014	2" Leaded Quadpack Carrier	А	December 1989
CO-015	Tray for Handling and Shipping of PQFP Packages	В	January 1993
CO-016	Tray for Handling and Shipping of PLCC Packages	В	November 1992
CO-017	Metric TAB Magazine Family	А	August 1991
CO-018	Metric TAB Tape Carrier Family	А	June 1992
CO-019	Magazine Family Metal Coinstack	А	June 1992
CO-020	Replaced by CS-008		March 1996
CO-021	Plastic Magazine Coinstack	А	August 1992
CO-022	Plastic Magazine Plug Family	А	August 1992
CO-023	Plug Family Coinstack Magazine	А	July 1993
CO-024	Replaced by CS-007		November 1994
CO-025	MCR Plug Family, Flat Plastic Tube (Magazine)	А	June 1993
CO-026	MCR Tube Family, Flat Plastic Tube (Magazine)	А	June 1993
CO-027	MQFP High Density Thin Matrix Tray for Shipping and Handling	В	March 1996
CO-028	Thick Matrix Tray for Handling/Shipping of Ball	В	October 1995
CO-029	Thin Matrix Tray for Shipping and Handling of Ball	Н	September 2002
	Grid Packages		-
CO-030	Thin Matrix Mini Tray	А	October 1995
CO-031	Thick Matrix Mini Tray	А	October 1995
CO-032	Thin Matrix Tray for Handling and Shipping Small	А	April 1996
	Outline J Lead Packages		
CO-033	Plastic Chip Carrier Tube Family	А	August 1998
CO-034	Low Profile Matrix Tray for Handling and Shipping	D	February 2003
	Thin Microelectronic Devices		

OUTLINE		ISSUE	
NUMBER	TITLE	LETTER	DATE
CO-035	Thin Matrix Tray for Shipping and Handling of	А	March 2006
	Advanced Memory Buffer		
CO-036	Shipping and Handling Tray for DDR5 DIMM	В	October 2021
	Microelectronic Assembly		

OUTLINE		ISSUE	
NUMBER	TITLE	LETTER	DATE
DO-1	Axial Lead, Flanged (see DO-210-AA)	А	Archived – JEP 95
DO-2	Axial Lead, Flanged		Archived – JEP 95
DO-3	Axial Lead, Flanged		Archived – JEP 95
DO-4	Axial Lead, Terminal Stud (see DO-203-AA)	А	
DO-5	Axial Lead, Terminal Stud (see DO-203-AB)	A	Archived – JEP 95
DO-6	Axial Lead, Flanged		Archived – JEP 95
DO-7	Axial Lead, Round Body (see DO-204-AA)	А	Archived – JEP 95
DO-8	Axial Lead, Terminal Stud (see DO-205-AA)	В	June 1971
DO-9	Axial Lead, Terminal Stud (see DO-205-AB)	В	June 1968
DO-10	Stud Mounted with Terminal		Archived – JEP 95
DO-11	Stud Mounted with Terminal		Archived – JEP 95
DO-12	Axial Lead, Flanged		Archived – JEP 95
DO-13	Axial Lead, Round Body (see DO-202-AA)	А	Archived – JEP 95
DO-14	Axial Lead, Round Body (see DO-204-AB)	А	Archived – JEP 95
DO-15	Axial Lead, Round Body (see DO-204-AC)	А	Archived – JEP 95
DO-16	Axial Lead, Round Body (see DO-204-AD)	А	Archived – JEP 95
DO-17	Axial Lead, Flanged		Archived – JEP 95
DO-18	Axial Lead, Round Body		Archived – JEP 95
DO-19	Disc Package		Archived – JEP 95
DO-20	Ceramic Cylinder with Strip Leads		Archived – JEP 95
DO-21	Press Fit		Archived – JEP 95
DO-22	Single-Ended Prong		Archived – JEP 95
DO-23	Double-Ended Prong		Archived – JEP 95
DO-24	Press Fit		Archived – JEP 95
DO-25	Ceramic Cylinder		Archived – JEP 95
DO-26	Axial Lead, Round Body (see DO-204-AE)	А	Archived – JEP 95
DO-27	Axial Lead, Contour-End (see DO-201-AA)	В	Archived – JEP 95
DO-28	Axial Lead, Flanged		Archived – JEP 95
DO-29	Axial Lead, Round Body (see DO-204-AF)	А	Archived – JEP 95
DO-30	Stud Mount with Axial Lead		Archived –J EP 95
DO-31	Circular Tab-Leads		Archived – JEP 95
DO-32	Axial Lead, Plastic		Archived – JEP 95
DO-33	Axial Lead, Single-Ended		Archived – JEP 95
DO-34	Axial Lead, Round Body (see DO-204-AG)	В	Archived – JEP 95
DO-35	Axial Lead, Round Body (see DO-204-AH)	В	Archived – JEP 95
DO-36	Single-Ended Plastic with Shielded Prong	А	Archived –J EP 95
DO-37	Single-Ended Plastic with Shielded Prong	А	Archived – JEP 95
DO-38	Flat-Based Cylinder without Prong	A	Archived – JEP 95
DO-39	Axial Lead, Plastic	А	Archived – JEP 95
DO-40	Cylinder with Perpendicular Lead	А	Archived – JEP 95
DO-41	Axial Lead, Round Body (see DO-204-AL)	А	Archived – JEP 95

OUTLINE		ISSUE	
NUMBER	TITLE	LETTER	DATE
DO-42	Cylinder without Prongs	А	Archived – JEP 95
DO-43	Flange-Based Package with Terminal	А	Archived – JEP 95
DO-44	Flange-Based Package with Terminal	А	Archived – JEP 95
DO-45	Axial Lead, Single-Ended	А	Archived – JEP 95
DO-200	Disc Type	E	July 1985
DO-201	Axial Type, Round Body, Tapered-End	В	November 2013
DO-202	Axial Leads, Round	А	Archived – JEP 95
DO-203	Stud-hex Base, Solid Terminals	В	March 1973
DO-204 AA-AH	Lead Mounted Family (Round Lead Axial)	В	January 1976
DO-204 AJ-AM	Lead Mounted Family (Round Lead Axial)	С	July 1997
DO-204 AN-AR	Lead Mounted Family (Round Lead Axial)	В	July 1985
DO-205	Stud-Hex Base, Flex Terminals	С	February 1987
DO-206 AA-AB	Lead Mounted Family (Flat Lead Axial)	А	Archived – JEP 95
DO-207 AA	Leadless Device Family	А	Archived – JEP 95
DO-208	Single-End Press-Fit, Flanged	А	December 1972
DO-209	Single-End Press-Fit, Solid Terminals	А	December 1972
DO-210	Lead Mounted Family (Flange Case)	А	Archived – JEP 95
DO-211	Cancelled - REPLACED by TO-244-AA-AB		
DO-212	Pill Family (Round Lead Axial)	А	Archived – JEP 95
DO-213	Leadless Family	D	September 1988
DO-214	Small Outline Plastic Surface Mount C-Bend	D	April 2003
DO-215	Small Outline Plastic Surface Mount Gull Wing	С	June 1998
DO-216	S-PDSO-G2 Gullwing Plastic Surface-Mount	А	October 1995
DO-217	GADB-N Button Rectifier	А	May 1996
DO-218	Power Outline Plastic Surface Mount C-Bend	С	April 2014
DO-219	Outline Plastic Surface Mount Flat	С	May 2015
DO-220	Small Outline Plastic Surface Mount	В	October 2004
DO-221	Thin Profile Plastic Small Outline Surface Mount	В	August 2018
DO-222	Very Thin Small Outline Plastic Surface Mount	А	May 2006

OUTLINE		ISSUE	
NUMBER	TITLE	LETTER	DATE
	Deal in line Family 7 (2) may Dear Greeting	D	Lana 1076
MO-001 AA-AD	Dual in-line Family 7.62 mm Row Spacing	D	June 1976
MO-001 AE-AH	Dual in-line Family 7.62 mm Row Spacing	D	June 19/6
MO-001 AJ-AM	Dual in-line Family 7.62 mm Row Spacing	F	June 1983
MO-001 AN-AP	Dual in-line Family 7.62 mm Row Spacing	В	October 1980
MO-002 AA-AH	Header Family .200" Pin Circle	В	October 1976
MO-002 AJ-AL	Header Family .200" Pin Circle	C	October 1976
MO-003 AA-AD	Replaced by MS-033 Variation AB	A	November 1999
MO-003 AE-AH	Replaced by MS-033 Variation AA	A	November 1999
MO-003 AJ	Replaced by MS-033 Variation AB	A	November 1999
MO-003 AK	Replaced by MS-033 Variation AA	A	November 1999
MO-004 AA	Replaced by MS-033 Variation AB	A	November 1999
MO-004 AB	Replaced by MS-033 Variation AB	A	November 1999
MO-004 AC	Replaced by MS-033 Variation AB	A	November 1999
MO-004 AD	Replaced by MS-033 Variation AA	A	November 1999
MO-004 AE	Replaced by MS-033 Variation AA	A	November 1999
MO-004 AF	Replaced by MS-033 Variation AB	A	November 1999
MO-004 AG	Replaced by MS-033 Variation AC	А	November 1999
MO-004 AH	Replaced by MS-033 Variation AC	А	November 1999
MO-004 AJ	Replaced by MS-033 Variation AB		
MO-004 AK	Replaced by MS-033 Variation AA	А	November 1999
MO-004 AL	Replaced by MS-033 Variation AC	А	November 1999
MO-004 AM	Flatpack Family .300" Width, .050" Pitch	С	November 1999
	RESCINDED		
MO-005	Grid Array Family, .125" Pitch	В	Archived – JEP 95
MO-006 AA-AD	Header Family 5.842 mm Pin Circle	С	October 1976
MO-006 AE-AH	Header Family 5.842 mm Pin Circle	D	October 1976
MO-007	Header Family, .141" Pin Circle	В	Archived – JEP 95
MO-008	Header Family, .100" Pin Circle	В	Archived – JEP 95
MO-009 AA-AB	Header Family, .200 Pin Circle	С	Archived – JEP 95
MO-010	Header Family, .065" Pitch	В	Archived – JEP 95
MO-011	Grid Array Family, 2.54 mm Pitch	В	Archived – JEP 95
MO-012 AA-AB	Quad Header Family, 2.54 mm Pitch	С	Archived – JEP 95
MO-013	Header Family, 11.89 mm Pin Circle	В	Archived – JEP 95
MO-014	Flange-Mounted Family Axial Lead	С	October 1976
MO-015 AA-AD	Dual In Line (DIP) Family 15.24 mm Row Spacing	D	June 1976
MO-015 AE-AH	Dual In Line (DIP) Family 15.24 mm Row Spacing	E	June 1977
MO-015 AJ-AM	Dual In Line (DIP) Family 15.24 mm Row Spacing	E	February 1981
MO-015	R-PDIP-T Dual Inline Plastic Family .600" Row	G	April 1993
	Spacing		-
MO-016	Dual In Line Plastic Family .900" Row Spacing	D	May 1990
MO-017	Axial Quad Family 2.54 mm Pitch	В	October 1976

OUTLINE		ISSUE	
NUMBER	TITLE	LETTER	DATE
MO-018	Flatpack Family 10.16 mm Width, .89 Pitch	С	June 1976
MO-019 AA	Replaced by MS-033 Variation AE	А	November 1999
MO-019 AB	Replaced by MS-033 Variation AF	А	November 1999
MO-019 AC	Replaced by MS-033 Variation AE	А	November 1999
MO-019 AD	Replaced by MS-033 Variation AF	А	November 1999
MO-019 AE	Flatpack Family 10.16 mm Width, 1.27 Pitch	D	November 1999
	RESCINDED		
MO-019 AF	Replaced by MS-033 Variation AF	А	November 1999
MO-020	Flatpack Family 12.70 mm Width, 1.27 Pitch	С	June 1976
MO-021	Flatpack Family 15.24 mm Width, 1.27 Pitch	С	June 1976
MO-022 AA-AD	Flatpack Family 17.780 mm Width, 1.27 Pitch	D	September 1977
MO-022 AE	Flatpack Family 17.780 mm Width, 1.27 Pitch	А	September 1977
MO-023	Flatpack Family 22.86 mm Width, 1.27 Pitch	С	June 1976
MO-024	Dual In Line (DIP) Family 12.70 mm Row Spacing	С	June 1976
MO-025	Flange Mounted Family Axial Lead 12.70 Pin Circle	В	October 1976
MO-026	Standard Dual-in-Line Family .400" Row Spacing	D	July 1991
	(Plastic) .070" Lead Pitch		
MO-027	Leadless Flatpack Family 1.27 mm Terminal Space	А	February 1977
MO-028	Dual In Line (DIP) Family 5.08 mm Row Spacing	В	October 1976
MO-029	Quad In Line (QUIP) Family 5.08/10.16 mm Row	В	October 1976
	Spacing		
MO-030	Quad In Line (QUIP) Family 19.05/23.50 mm Row	В	October 1976
	Spacing		
MO-031	Quad In Line (QUIP) Family 5.08/10.16 mm Row	D	October 1979
	Spacing		
MO-032 AA-AF	Flatpack Family 16.64 mm Width, 1.27 Pitch	С	February 1981
MO-033	Quad In Line (QUIP) Family 17.78/22.86 mm Row	В	February 1981
	Spacing		
MO-034	Quad In Line (QUIP Family) .750/.925" Row	С	June 1990
	Spacing		
MO-035	Single In Line (SIP) Family	А	September 1980
MO-036	Ceramic Dual-In-Line (DIP) Family .300" Row	В	November 1999
	Spacing		
MO-037	Replaced by MS-031		
MO-038	Replaced by MS-032		
MO-039	Ceramic Side Leaded Dual In Line (DIP) Family	А	April 1981
	22.86 mm Row Spacing		-
MO-040	Power Module	С	May 1983
MO-041 AA-AF	.050" Pitch Leadless Rectangular Chip Carrier	С	February 1995
	Family (R-CQCC-N)		
MO-042	.050" Center Leadless Rectangular Chip Carrier	А	February 1983
	Type F		-

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
			2
MO-043	Dual In Line Package 19.05 mm Row Spacing	А	September 1984
MO-044	Leaded Ceramic Chip Carrier .050" Center	А	September 1984
MO-045	Single In Line Power Module	А	September 1984
MO-046	Small Outline (SO) Package Peripheral Terminals	В	November 1984
	5.30 mm (.200") Wide Body		
MO-047	Plastic Chip Carrier (PCC) Family .050"	В	November 1988
	Leadspacing, Square		
MO-048	Plastic Flange-Mounted Header Family Multilead	А	February 1987
	Registration		j
MO-049	Not Published		
MO-050	Not Published		
MO-051	Not Published		
MO-052	Replaced by MS-016		
MO-053	Replaced by MO-069		September 1988
MO-054	Zig-Zag (ZIP) In Line Family 2.54mm Row Spacing	А	June 1986
MO-055	Ceramic Single In Line (SIP) Family	А	August 1986
MO-056	Ceramic .025" Center Chip Carrier	А	August 1986
MO-057	Ceramic .020" Center Chip Carrier	А	August 1986
MO-058 AA	Replaced by MS-030 AF		0
MO-058 AB	Replaced by MS-030 AG		
MO-059	Small Outline (SO) Package Family 8.4 mm Body	В	January 1987
	Width (Plastic)		5
MO-060	.040" 132 Pin Quad Flatpack	В	November 1989
MO-061	Replaced by MS-027		June 1995
MO-062	Ceramic Chip Carrier 0.25" Center	А	April 1987
MO-063	Plastic Small Outline J-Lead (SOJ) .350" Body	А	April 1987
MO-064	30 Circuit Pluggable Single Inline Package (SIP)	С	September 1992
	Tabs on .100" Centers		-
MO-065	Plastic Small Outline J-Lead (SOJ) .300 Body	А	May 1987
	Family		•
MO-066	S-CPGA-P Pin Grid Array Family, .100" Pitch	С	April 1994
	(Small Outline)		-
MO-067	Pin Grid Array Family, .100" Pitch (Large Outline),	В	June 1993
	S-CPGA-P		
MO-068	Edge Clip SIP Module Family .100 Row Centers	В	August 1991
MO-069	Plastic Quad Flat Pack .025" Lead Spacing	В	October 1990
	(Gullwing)		
MO-070	.375" Width Flatpack NOT PUBLISHED	А	August 1987
MO-071	Plastic Thin Lead Package	В	July 1989
MO-072	Zig-Zag Inline Family (ZIP) 0.500" Max Seated Height	В	September 1990
MO-073	Ceramic Top Brazed Dual In Line (DIP) Family	А	November 1987
	.900 (22.86) Row Spacing		

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
MO 074	Commis Dottom Brazed Dual In Line (DID) Family	٨	November 1097
WIO-074	900 (22 86) Row Spacing	A	November 1987
MO-075	.50 Center Non-Hermetic Leadless Chip Carrier	А	December 1987
	Quad Series		
MO-076	.050 Center Non-Hermetic Leadless Chip Carrier	А	December 1987
MO-077	Plastic Small Outline J-Lead Package Family (SOJ),	D	November 1994
	.300" Wide Body, .050" Lead Pitch		
MO-078	Hermetic Flange-Mounted Header Family	А	February 1988
	(Peripheral Terminals) Five Lead 2.54 Spacing		
MO-079	Flanged Family Peripheral lead .125 Pitch	A	March 1988
MO-080 AA-AB	ZIP Module Family 0.050" Pin Centers 0.100" Row	А	September 1988
MO 091	Centers	٨	March 1000
MO-081	Ceranic Quadpack Failiny .050 Pitch	A	March 1988
MO-082	(Gullwing)	А	May 1988
MO-083	.100" Center Plastic Pin Grid Array Family	А	December 1988
MO-084	Ceramic Quad Flat Pack 0.50" Lead Spacing	А	July 1988
	(Gullwing)		
MO-085	.040" Center Rectangular Leadless Package	А	July 1988
	(Staggered Terminals)		
MO-086	Low Profile Plastic Quad Flat Pack Family .025 Lead Spacing (Gullwing)	В	June 1990
MO-087	"I" Leaded Ceramic Cercuad Package Family -	В	August 1991
100 007	.050" Pitch	Ъ	August 1991
MO-088 AA-AF	Small Outline J-Lead (SOJ) .300 Body Family	А	June 1988
	(MS-113 body)		
MO-089	Plastic Quad Flat Pack .050" Lead Spacing	А	November 1988
	(Gullwing)		
MO-090 AA-AF	Ceramic Quadpack Family .025" Lead Spacing	В	September 1989
MO-091	Plastic Small Outline J-Lead (SOJ) .350 Body	А	February 1989
	Family		
MO-092	6.35 Mm Width Cerpak Registration	А	April 1989
MO-093	Flange-Mounted Header, 5-Lead	А	February 1990
MO-094	Molded Carrier Ring Family	С	March 1993
MO-095	Dual Incline (Wide Body) Plastic Family .300" Row	А	September 1989
	Spacing		
MO-096	Flange-Mounted Header, 7-Lead	А	February 1990
MO-097	Flange-Mounted Family Axial Lead .500" Pin Circle	A	July 1989
MO-098	Braze Lead Flatpack Registration	А	December 1989
MO-099	Small Outline (SO) Family Peripheral	А	October 1989
MO-100	Multilayer Ceramic Quad Flatpack .20 Spacing	А	November 1989

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
	Gullwing (256 leads)		
MO-101	48 Pin Flatnack Ton Brazed	А	November 1989
MO-102	Tape Quad Flatpack RESCINDED	A	November 1992
MO-102	Replaced by MS-032	B	August 1999
MO-104	Ceramic Quad Elatnack, 0.25" Pitch, Gullwing	A	August 1991
	Leadform		1108000 1991
MO-105	Thin Small Outline J-Lead (TSOJ) .300" Body,	А	August 1990
	0.050" Lead Pitch		e
MO-106	Flatpack Family .535" Length, .030 Pitch	А	April 1990
MO-107	Ceramic Multilayer Leaded Chip Carrier .050"	А	May 1990
	Pitch, J-Bend		
MO-108	Metric Plastic Quad Flat Pack Family, 1.0, 0.8, 0.65	С	August 1996
	Pitch PQFP-G/MQFP		
MO-109	Molded Carrier Ring Family	В	March 1993
MO-110	Round Lead, "J" form .050" Center Ceramic Chip	А	July 1990
	Carrier		
MO-111	Round Lead, Gullwing .050" Center Ceramic Chip	А	July 1990
	Carrier		
MO-112	Metric Plastic Quad Flatpack Family 3.9 mm	В	September 1995
	Footprint	_	
MO-113	Ceramic Quadpack Family 0.25" Lead Spacing With	D	August 1997
	Ceramic Nonconductive Tie Bar	a	I 1007
MO-114	Glass Sealed CQFP Family (GQFP-G)	C	January 1996
MO-115	32 Ld. Flatpack .480" Wide	A	November 1990
MO-116	Pluggable Single In-Line Memory Module (SIMM)	В	June 1998
MO 117	With Tabs on .050 Centers	٨	June 1000
MO-117	Small Outline Gullead 12 mm Body 0.80 mm Lead	А	June 1990
MO 119	Spacing Shrink Small Outling Dealeges Femily, 0.25" Load	D	Juna 1002
MO-118	Ditab 200" Wide Dody Width (P DDSO C)	D	June 1995
MO 110	Plicit .500 Wide Body Width (K-PDSO-O) Plastic Small Outline (SO) Package Family With	В	May 1002
WIO-119	300" Body Width	D	Way 1992
MO 120	Distic Small Outline (SO) Package Family With	В	May 1002
WIO-120	350" Body Width	D	Wiay 1992
MO-121	Plastic Small Outline (SO) Package Family With	B	May 1992
MO 121	330'' Body Width	Б	Widy 1992
MO-122	R-PDIP-T Thin Dual In Line Family 300" Row	А	August 1992
110 122	Spacing (Plastic)	11	Tugust 1772
MO-123	Small Outline J-Lead, 12 mm Body 0 80 mm Lead	А	June 1991
	Spacing		
MO-124	Small Outline J-Lead Package Family (SOJ) 12.70	В	January 1994
	mm Body,1.27 mm Lead Spacing		2

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
MO-125	Ceramic Quad Flatpack .025" Pitch Gullwing	А	June 1991
MO 126	Leadform P CDCC NL and loss Small Outling Coronia Chin	D	Juna 1002
WIO-120	Carrier 400" Body 050" Pitch	D	June 1995
MO-127	Power Dual In-line	А	February 1992
MO-128 AA-BO	.100" Center Staggered Pin Grid Array Family	C	January 1997
······································	(Large Outline)	-	j
MO-129	Top Brazed Ceramic Leaded Chip Carrier (.020"	А	September 1992
	Lead Pitch) with Plastic Non-Conductive Tie Bar		1
MO-130	Top Brazed Ceramic Leaded Chip Carrier (.015"	А	September 1992
	Lead Pitch) with Plastic Non-Conductive Tie Bar		-
MO-131	Top Brazed Ceramic Leaded Chip Carrier (.025"	А	September 1992
	Lead Pitch) with Plastic Non-Conductive Tie Bar		
MO-132	Replaced by MS-025A		
MO-133	Replaced by MS-024		January 1995
MO-134	Ceramic Quad Flatpack Family (CQFP) 0.50 mm	А	May 1992
	Lead Pitch with Ceramic Nonconductive Tie Bar		
MO-135	Thin Small Outline Package 12.70 mm Body Family	С	November 1993
	(R-PDSO-G/TSOP II)		
MO-136	Replaced by MS-026	-	1 2010
MO-137	Plastic Shrink Small Outline Package (SSOP)	E	March 2010
120	Family 0.025" pitch 0.150" Body Width		L 1002
MO-138	16 Lead Flange Mounted Ceramic Power Package	А	June1993
MO 120	(Type I), R-CDFM-110 16 Load Elenge Mounted Commis Deuren Deekees	٨	Juna 1002
MO-159	(Type 2) B CDEM T16	A	June1995
MO 140	(1ype 2), R-CDFW-110 18 Lead Flange Mounted Caramic Dower Dackage	٨	June1003
WIO-140	R_CDEM_T16	A	June1995
MO-141	Vertical Surface Mount Package () 50 mm Lead	Δ	March 1993
	Pitch R-PSIP-X24	11	
MO-142	Thin Small Outline Package Type I. R-PDSO-	D	July 2000
1110 112	G/TSOPII	2	001 2000
MO-143	Replaced by MS-029		June 1997
MO-144	Leadless Small Outline Ceramic Chip Carrier .350"	А	June 1993
	Body, .050" Pitch, R-CDCC-N		
MO-145	S-CPGA-B/SMTPGA .050 Center Ceramic Surface	А	June 1993
	Mount Pin Grid Array Family Registration		
MO-146	Ceramic Flatpack Family .380" Width, .025 Pitch	А	July 1993
	(R-GDFP-F)		
MO-147	Small Outline J-Lead Ceramic Chip Carrier .415"	А	July 1993
	Body, .050" Lead Spacing (R-CDSO-J)		

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
MO-148	Multichip Module Ceramic Quad Flatpack (S- CQFP)	А	June 1993
MO-149	Tape Ball Grid Array Family	F	October 2003
MO-150	Plastic Shrink Small Outline Package (SSOP) -	В	January 1994
	5.3mm Body Width, 0.65mm Pitch, 1.25mm Lead Length (R-PDSO-G)		
MO-151	Replaced by MS-034		
MO-152	Plastic Shrink Small Outline Package (SSOP),	С	January 1996
	R-PSDO-G/SSOP		
MO-153	Plastic Thin Shrink Small Outline Package (SSOP)	G	January 2018
	R-PDSO-G/TSSOP/HTSSOP		
MO-154	Shrink Small Outline Package Family, 0.4 mm and	С	April 1997
	.5 mm Lead Pitch, 3.9 mm Wide Body		-
MO-155	5-Lead Small Outline Plastic (SOP) Package	А	November 1993
MO-156	Square Ceramic Ball Grid Array Family 1.00, 1.27,	С	April 2005
	and 1.50 mm Pitch		•
MO-157	Rectangular Ceramic Ball Grid Array Family 1.00,	С	April 2005
	1.27, and 1.50 mm Pitch		-
MO-158	CBGA-X Ceramic Column Grid Array Family -	D	April 2002
	Square		±
MO-159	Ceramic Column Grid Array Family - Rectangular	В	June 1999
MO-160 AA-CC	72-Contact Dual Inline Memory Module (DIMM)	В	September 1995
	Family, 1.27 Lead Centers		L.
MO-161	100 and 168 Pin Dual Inline Memory Module	Ff	January 2003
	(DIMM) Family with Multiple Keyways, 1.27 mm		•
	Contact Centers		
MO-162	Plastic Flat Pack/Heat Slug Package 8 mm Pitch 48	А	November 1993
	Leads (S-PTFP-G48)		
MO-163	Replaced by MS-028		December 1997
MO-164	Plastic Small Outline Package, 9.90 mm Wide Body	А	January 1994
	Family (R-PDSO-G)		
MO-165	Plastic Small Outline J-Lead, 10.15mm Body	С	September 1996
	Family, .8mm Pitch		-
MO-166 AA-AF	Plastic Small Outline Heat Slug Package, 20, 24, 30,	D	November 1999
	36 Leads		
MO-167	Pluggable Dual Inline Module, 1.27 mm Lead	С	October 1997
	Centers 128-Pins		
MO-168 AA-AB	Plastic Isolated Flange-Mounted Header Family	А	January 1994
MO-169	Plastic Surface Mounted Header Family	В	November 2000
MO-170	68-Pin Card	А	February 1995
MO-171	88-Pin Card	А	February 1995

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
MO-172	Dual Inline Memory Module (DIMM) Family 112 & 300 Pin 1 27 mm Pitch	D	April 1999
MO-173	TFH-PQFP-G/TQHS Thin Quad Heat Spreader	А	October 1995
MO-174	Plastic Small Outline Package, 70-pin .8 mm Pitch	А	January 1996
MO-175	(R-PDSO-G/SOP) Plastic Small Outline Package, 12.6 mm Body, 1.27	А	September 1995
	mm Lead Spacing		
MO-176	Ceramic Zig-Zag Inline Family (2.54 Row Spacing)	A	March 1995
MO-177	(DIMM) Family, 0.65 mm Lead Centers RESCINDED	A	July 2001
MO-178	Plastic Small Outline Package (SOT/SP), 5 Leads	D	September 2020
MO-179	Dual Inline Memory Module (DIMM) Family 1.00 Lead Centers (278-pin)	А	October 1995
MO-180	Plastic Small Outline Package (SOP) 13.3 mm Body Width	В	February 2001
MO-181	Metric Small Outline 16 mm Wide Body J-Lead	А	January 1996
MO-182	Metric Thin Small Outline 16.00 mm Wide Body	С	September 1996
MO-183	Thin Small Outline Package Type I 0.55 mm Lead Pitch (TSOP I)	А	January 1996
MO-184	Plastic Small Outline Heat Slug Package	В	November 1999
MO-185	72 Pin Staggered Dual Inline Module (SDIM) Family 1 27 Lead Centers	Ā	August 1996
MO-186	Solid State Floppy Disk Card (SSFDC)	С	March 1999
MO-187	Plastic Thin Shrink Small Outline Package 0.65 & 0.50 Pitch	F	September 2010
MO-188	Power POFP Heat Slug Package (H-POFP - G)	В	February 2000
MO-189	Plastic Quad Flat Heat Slug Package (2.0mm Thick 2 00 mm Footprint Quad & Dual-Sided Leads)	А	March 1996
MO-190	Small Outline Dual Inline Memory Module (DIMM)	D	January 2001
MO-191	Dual Inline Memory Module (DIMM) Family 1.27	А	December 1996
MO-192	Low Profile Ball Grid Array Family	F	August 2003
MO-193	Plastic Thin Shrink Small Outline Package (Shrink	G	February 2021
MO-194	Plastic Thin Shrink Small Outline Package 0.40mm Lead Pitch	В	November 1997
MO-195	Thin Fine Pitch Ball Grid Array, 0.50mm Pitch	D	May 2006

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
MO 106	Direction Hillers This Great Orections No. 1 and Declares	C	Law e 1009
MO-190 MO-107	Plastic Ultra-Thin Small Outline No-Lead Package	C D	June 1998 Nevember 1007
MO-197	Plastic Ultra-Thin Small Outline No-Lead Package	В	November 1997
MO-198	PQFP-B 3-THEF FAMILY	A	April 1997
MO-199	Low Profile Small Outline J-Lead Package (LSOJ)	B	June 1999
MO-200	Small Outline J-Lead Package Assembly 2 High/4 High Stack	В	June 1999
MO-201	2 High/4 High Stacked TSOP II INACTIVATION NOTICE	А	June 2003
MO-202	Vertical Zig Zag Surface Mount Package 0.40mm Lead Pitch	А	March 1998
MO-203	Plastic Thin Shrink Outline Package (Shrink SOT)	С	August 2010
MO-204	Plastic Quad Flat Package Outline With Exposed	B	May 2001
	Heat Sink	2	11149 2001
MO-205	Low Profile, Fine Pitch, Ball Grid Array Family, 0.80mm Pitch (Sq. & Rect.)	F	April 2003
MO-206	Dual Inline Memory Module (DIMM) Family 184 Pin DDR 1 27mm Contact Centers	Ε	January 2006
MO-207	Square & Rectangular Die-Size Ball Grid Array	Ν	June 2013
MO-208	Plastic Thin Fine Pitch Quad Flat No Lead Package	С	November 2001
MO-200	Plastic Thin The Then Quad That No Lead Tackage	Δ	November 1998
MO_{-210}	Fine Pitch Ball Grid Array Family Rectangular 0.80		January 2021
WIO-210	mm Pitch	Q	
MO-211	Die Size Ball Grid Array	С	June 2004
MO-212	Rectangular Plastic Quad Flat Package Outline 1.0mm Thick Body 3.20 Footprint	A	November 1998
MO-213	Horizontal Staggered Surface Mount Package 0.40mm Lead Pitch	А	November 1998
MO-214	Micro Dual Inline Memory Module Family, 0.5mm Lead Centers	В	September 2002
MO-215	SDRAM Dual Inline Memory Module (DIMM) Family, 1.00 mm Contact Centers INACTIVATION NOTICE	А	November 2000
MO-216	Plastic Bottom Ball Grid Array Family, 0.80 mm Pitch Square Family	G	January 2021
MO-217	Very Very Thin Quad Bottom Terminal Chip Carrier Family	В	November 2001
MO-218	Plastic Flange-Mounted, Staggered Header Family	А	October 1999
MO-219	Low Profile, Fine Pitch, Ball Grid Array Family.	G	January 2007
/	0.80 mm Pitch. (SO.& RECT.)	-	,
MO-220	Thermally Enhanced Plastic Very Thin and Very Very Thin Fine Pitch Quad Flat No Lead Package	K.01	August 2011

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
MO-221	Extremely Thin Profile Two Row Cavity Down 0.50	С	May 2001
MO-222	Very Thin Profile. Fine Pitch Land Grid Array	B.01	December 2010
1110 222	Family, 0.50/0.65 mm PITCH, SQ/RECT	D .01	
MO-223	Plastic Thin Shrink Small Outline Package	А	April 2000
	(Shrink SOT)		
MO-224	200 Pin DDR S.O. DIMM 0.60 mm Lead Centers	E	November 2006
MO-225	Very Thin Profile, Fine Pitch, Ball Grid Array	С	August 2007
MO 226	Family 0.50/0.65 mm Pitch, SQ/REC1 Plastic Small Outling Heatslug Package 7.5mm	D	Echrugry 2001
MO-220	Body Wide 1 0mm Lead Pitch	D	reditially 2001
MO-227	DDR SRAM DIMM 1.00 mm Contact Centers	А	May 2003
	INACTIVATION NOTICE		
MO-228	Thin, Fine-Pitch Ball Grid Array Family, Dual Pitch	А	March 2001
MO-229	Thermally Enhanced Plastic Very Thin and Very	F	August 2012
	Very Thin Fine Pitch Dual Flat No Lead Package		
MO-230	Plastic Small Outline with Exposed Heat Sink	А	March 2001
MO-231	Plastic Surface Mounted Header Family 21.50mm	А	August 2001
	Body Width, 1.40mm LEAD PITCH		
MO-232	Low Profile Plastic Dual Flat No Lead Package	A	August 2001
MO-233	Rectangular Die-Size, Fine Dual Pitch Ball Grid Array Family	С	February 2003
MO-234	Bottom Grid Array, Ball, 1.00 mm Pitch	Е	June 2018
	Rectangular Family		
MO-235	Header Family Surface Mounted (Peripheral	В	February 2003
MO-236	Plastic Illtra and Super Thin Small Outline Non-	C	March 2010
WIO-250	Leaded Package	C	Waten 2010
MO-237	DDR2 SDRAM DIMM (Dual Inline Memory	G.01	April 2011
	Module) Family 1.00mm Contact Centers		1
MO-238	Stacked TSOP II Package Family (2 High)	А	February 2003
MO-239	Thermally Enhanced Plastic Very Thin Dual Row	А	November 2002
	Fine Pitch Quad Flat No Lead Package		
MO-240	Thermally Enhanced 8 Lead 1.27 & 0.65MM Pitch,	С	August 2012
	Low Profile Plastic Dual Flat No Lead Package	D	
MO-241	Dual Compatible Thermally Enhanced Plastic Very	В	August 2003
MO 242	I nin Fine Pith Quad Flat No Lead Package	C	Soutombor 2008
MO-242	Family 80mm Pitch	C	September 2008
MO-243	Thermally Enhanced Plastic Very Thin and Very	А	August 2003
	Very Thin Fine Pitch Bumped Ouad Flat No lead		
MO-244	244 Pin DDR2 Mini DIMM 0.60 Lead Centers	С	February 2008

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
MO-245	High Profile Plastic Thermally Enhanced Enlarged	А	September 2003
MO-246	Rectangular Fine Pitch Thin Ball Grid Array 0.65	G	February 2015
MO-247	Plastic Quad No-Lead Staggered Multi-Row Packages	D	May 2007
MO-248	Thermally Enhanced Plastic Ultra Thin and Extremely Thin Fine Pitch Quad Flat No Lead Package	Ε	June 2006
MO-249	Thin SO Package 8.89mm Body Family	А	January 2004
MO-250	Thermally Enhanced Plastic Very Thin and Very Very Thin Fine Pitch Bumped Quad Flat No Lead Package	А	November 2003
MO-251	Thermally Enhanced Plastic Very Thick Quad Flat No Lead Package	А	February 2004
MO-252	Plastic Very Very Thin Ultra Thin and Extremely Thin Fine Pitch Dual Small Outline Non-Leaded Package	D	March 2010
MO-253	14 & 16 Lead Screw Mount and Surface Mount Power Package	В	February 2008
MO-254	Thermally Enhanced Plastic Low and Thin Profile Fine Pitch Quad Flat No Lead Package	А	February 2004
MO-255	Plastic Very Very Thin Ultra Thin and Extremely Thin Fine Pitch Quad Flat Small Outline Non- Leaded Package	В	October 2005
MO-256	FB DIMM Family 1.00mm Contact Centers	F	June 2007
MO-257	Plastic Fine Pitch Quad No-Lead Staggered Two Row Thermally Enhanced Package Family	В	May 2005
MO-258	200 PIN DDR Mini DIMM 0.60 Lead Centers	А	December 2004
MO-259	Very Very Thin Small Outline Package Family	А	March 2005
MO-260	DDR and DDR2 Micro DIMM Mezzanine 214 Pin 0.4mm Lead Centers	С	January 2007
MO-261	Thick & Very Thick Fine Pitch Rectangular Ball Grid Array Family 0.80mm Pitch	А	June 2005
MO-262	Thermal Enhanced (Top Side) Plastic Very Thin and Very Very Thin Fine Pitch Quad Flat No Lead Package	А	September 2005
MO-263	Plastic Very Thin and Very Very Thin Fine Pitch Quad Flat No Lead Package	А	September 2005
MO-265	Thermally Enhanced Plastic Very Thin Fine Pitch Quad Flat No Lead Package Including Corner Terminals	А	November 2005

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
MO-266	Very Thin, Fine-Pitch, Stackable Ball Grid 0.50 mm Ball Pitch Array Family	C	January 2009
MO-267	Thermally Enhanced Plastic Very Thin Fine Pitch Quad Flat No Lead Package	В	March 2006
MO-268	204 Pin DDR3 S.O. DIMM 0.60 Lead Centers	Е	March 2014
MO-269	DDR3 SDRAM DIMM 1.00mm Contact Centers	Ι	February 2014
MO-270	Extra Thin Profile, Fine Pitch, Internal Stacking Module (ISM) With Single Interconnect Array 0.75/0.80 mm Pitch SQ/RECT	В	June 2008
MO-271	Exposed Pad Plastic Small Outline Family 7.60 mm Body Width	А	May 2006
MO-272	Low Profile Exposed Pad Plastic Small Outline Family 3.90mm Body Width	А	May 2006
MO-273	Upper POP Package, Square, Fine Pitch, Ball Grid Array (0.65 and 0.50 mm Pitch)	С	March 2011
MO-274	DDR1/DDR2 16b/32b Small Outline Dual Inline Memory Module (SO-DIMM) Family 0.8 Lead Centers	D	October 2014
MO-275	Low Profile, Fine Pitch Ball Grid Array Family (SO)	A.01	July 2011
MO-276	Fine Pitch Ball Grid Array Family, Rectangular, 0.50mm Pitch FR-XBGA	Р	January 2021
MO-277	13 Pin Full Size MultimediaCard (MMC) Outline- MMCplus 32 X 24 X 1.4mm	А	September 2006
MO-278	13 Pin Reduced Size MultimediaCard (MMC) Outline-MMCmobile 18 X 24 X 1.4mm	А	September 2006
MO-279	10 Pin Micro Size MultimediaCard (MMC) Outline- MMCmicro 14 X 12 X 1.1mm	А	September 2006
MO-280	Ultra Thin and Very, Very Thin Profile, Fine Pitch Ball Grid Array Family (SQ.)	А	September 2006
MO-281	DDR2 SDRAM DIMM (Dual Inline Memory Module) Family, Flex-Based, 1.00mm Contact Centers	А	November 2006
MO-282	FB DIMM Family, Flex Based, 1.00 mm Contact Centers	А	January 2007
MO-283	Plastic Super-Thin And Die-Thin Profiles RFID Dipole Straps	В	January 2008
MO-284	Thin, Fine-Pitch, Rectangular Dual Pitch Ball Grid Array Family 0.80mm x 1.00mm Pitch	А	May 2007
MO-285	Very Thin Fine-Pitch Ball Grid Array Family Rectangular 0.50/0.65/0.80 mm Pitch	А	August 2007

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
MO-286	Plastic Small Outline, Wide Body SOIC, 7.5 Body Width, 0.65 Pitch	В	January 2015
MO-287	Small Scale, Plastic, Ultra, Extra and Super Thin, Fine Pitch, Dual Small Outline, No Lead Package	А	September 2007
MO-288	Small Scale Plastic Ultra Extra and Super Thin Fine Pitch Quad Flat No Lead Package (With Optional Thermal Enhancements)	В	September 2009
MO-290	DDR3 SDRAM DIMM Family Flex-Based, 1.00mm Contact Centers	А	November 2007
MO-291	Very Thin Fine Pitch Plastic Quad Flat Package 2.00mm Footprint	В	December 2008
MO-292	Very Thin Fine Pitch Plastic Quad Flat Package, 2.00mm Footprint	C	April 2010
MO-293	Plastic, Ultra, Extra and Super Thin Fine Pitch Dual Small Outline, Flat, Leaded Package	А	December 2008
MO-294	Very Thin Profile, Fine Pitch, SQ Bump Grid Array Family	А	December 2008
MO-295	Thin Profile Interstitial Fine Pitch Ball Grid Array Family (SQ)	Α	January 2009
MO-296	Scalable Quad Flat No-Lead Packages, Square and Rectangular	В	January 2012
MO-297	SLIM LITE SSD Assembly	А	May 2009
MO-298	Thin, Very-Thin, Very Very Thin Profile Fine Pitch Ball Grid Array Family 0.40 mm Pitch	А	June 2009
MO-299	Surface Mount Power Package, Fused Leads	В	January 2015
MO-300	mSATA SSD Assembly	С	March 2015
MO-301	Standard & Low, Fine Pitch Rectangular BGA Family 0.65mm Pitch	А	May 2010
MO-302	Very Thin Fine-Pitch Fully Overmolded Stackable Ball Grid Array Family 0.4mm Ball Pitch	С	August 2016
MO-303	Land Grid Array, Rectangular, 0.5 mm Pitch	В	March 2012
MO-304	100/170 Ball Grid Array Family Rectangular 1.0mm Pitch	D	July 2013
MO-305	Wide I/O Micropillar Grid Array Package (MPGA)	С	October 2013
MO-306	Flange Mounted Family Surface Mount (Peripheral Terminals)	А	February 2011
MO-307	Dual-Pitch Rectangular BGA Package 0.50mm X 0.65mm Pitch	A	December 2011
MO-308	Thick Thermally Enhanced Fine Pitch Square BGA Family	A	April 2012
MO-309	200 PIN DDK4 DIMINI U.85mm Pitch	F	March 2015

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
MO-310	256 Pin DDR4 SODIMM and GDDR5M Outline () 50	C	February 2014
WIC 510	mm Pitch	C	1 cordary 2014
MO-311	Dual-Pitch Very Thin Profile Rectangular Fine Pitch BGA Package 0.80 mm X 0.65 mm Pitch	Е	February 2020
MO-312	4 Lead Flat and Gullwing Surface Mount Power	А	February 2013
	Package		
MO-313	Fine Pitch BGA Family Square 0.50mm Pitch	A	August 2014
MO-314	288 Pin DDR4 Mini DIMM, 0.50mm Pitch	A.01	May 2015
MO-315	Dual Pitch Number BGA Family, Square, 0.80 mm Major, 0.65 mm Minor Pitch	A	February 2015
MO-316	HBM Micropillar Grid Array Package (MPGA)	В	April 2019
MO-317	Upper POP BGA Square 0.40MM Pitch	С	January 2018
MO-318	BGA, Square, 1.00 MM Pitch	В	January 2017
MO-319	6 Lead Surface Mount Power Package with Fused Leads	А	February 2016
MO-320	12 Pin UES Card 0.91 MM Pitch	B	September 2020
MO-321	Upper PoP BGA Family Square 0.50 MM Pitch (S-	A 01	March 2017
110 521	XBGA)	11.01	
MO-322	Upper PoP BGA Family Square 0.65 MM Pitch (S- XBGA)	A.01	March 2017
MO-323	Upper PoP BGA Family Square 0.40 MM Pitch (R-XBGA)	A.01	March 2017
MO-324	Lower PoP BGA Family Square 0.50 MM Top 0.50	А	August 2016
MO 325	MM DOUDIN FIICH (S-ADGA) Lower DoD BGA Family Square 0.65 MM Top 0.50	۸	August 2016
WIO-325	MM Bottom Pitch (S-XBGA)	Λ	August 2010
MO-326	Lower PoP BGA Family Square 0.80 MM Top 0.50	А	August 2016
MO 227	MM Bottom Pitch (S-XBGA)	٨	Sentember 2016
MO-327	9 Lead Surface Mount Power Package, 1.2 mm Pitch H-PSOF	A	September 2016
MO-328	Ball Grid Array Family, Rectangle, 0.755 mm Pitch	В	February 2020
MO-329	288 Pin DDR5 DIMM, 0.85 MM Pitch	D	September 2021
MO-330	Ball Grid Array Family Rectangular, 0.60 mm x	А	June 2018
	0.70 mm Pitch PDSO-F2		
MO-331	Bottom Grid Array Ball, Square, 1.00 mm Pitch	А	June 2018
MO-332	Plastic Multi Small Outline, 17 Terminal, 1.20 mm	А	August 2018
	Pitch Package. PMSO-E17		
MO-333	Plastic Bottom Flatpack 35 Terminal Package. POFP-N35	А	August 2018
MO-334	Plastic Single Sided Hardware 7 Wire 1.2 mm Pitch Package. P-PSXH-W7_I120	А	September 2018

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MO-336	Plastic Bottom Grid Array, Ball 0.70 mm Pitch,	А	November 2018
	Square Family		
MO-337	262 Pin SODIMM, 0.50 mm Pitch Package	А	April 2019
MO-338	Plastic Bottom Grid Array Ball, 0.80 MM x 0.70	А	September 2019
	MM Pitch Rectangular Family Package		
MO-339	Plastic Bottom Flatpack 28 Terminal Package	А	September 2019
MO-340	Plastic Dual Small Outline Surface Terminal,	А	October 2019
	Wettable Flank Package		
MO-341	Plastic Quad Flatpack, 8 Terminal, 1.27 mm Pitch	А	October 2019
	Package		
MO-342	Plastic Bottom Grid Array Ball, 0.65 mm Pitch	А	January 2020
	Square Family Package		
MO-343	Plastic Dual Small Outline Surface, 2 Terminal,	А	March 2020
	Wettable Flank Package		
MO-344	Upper Pop Plastic Bottom BGA 0.40MM Pitch	А	August 2020
	Rectangular Family Package		0
MO-345	Plastic Dual Small Outline Gull Wing Package, 1.10 mm	А	October 2020
	Thick		
MO-346	Plastic Quad Flatpack, 0.65 mm Pitch, 3.30 mm Body,	А	November 2020
	Square Family Package		
MO-347	39 Pin Removable Memory, 1.00 mm Pitch	А	March 2021
	Microelectronic Assembly		
MO-348	Metal Enclosure for SSD Devices, E1.S and M.2	А	July 2021

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SO-001	240 Pin DDRII SDRAM, 1.00mm Contact Centers	В	July 2003
SO-002	244 Pin MINIDIMM 0.60mm Lead Centers	В	February 2008
SO-003	FB DIMM 240 Position Socket Outline 1.00mm	В	August 2006
	Contact Centers		U
SO-004	Connector Outline for DDR and DDDR2 Micro	А	May 2005
	DIMM Mezzanine 214 Pin 0.4mm Lead Centers		·
SO-005	200 Pin Mini DIMM 0.60 mm Lead Centers	А	September 2005
SO-006	204 Pin SO-DDR3 SDRAM, 0.60mm Contact	В	October 2007
	Centers, Socket Outline		
SO-007	DDR3 DIMM 240 Position Socket Outline 1.00mm	В	September 2008
	Contact Centers		-
SO-008	144 Pin, DDR1/DDR2 16b/32b Small Outline Dual	В	October 2012
	Inline Memory Module (SO-DIMM) Family, 0.8		
	Lead Centers, Dual Notch, Socket Outline		
SO-009	DDR2 DIMM 240 Pin SMT Socket Outline	А	March 2007
	1.00mm Contact Centers		
SO-011	240 Pin DDR2 DIMM 1.00 mm Contact Centers	А	September 2007
	Press Fit Socket Outline		
SO-012	240 Pin DDR3 DIMM 1.00 mm Contact Centers	А	September 2007
	Press Fit Socket Outline		
SO-013	240 Pin FBDIMM 1.00 mm Contact Centers Press	А	September 2007
	Fit Socket Outline		
SO-014	DDR3 DIMM 240 Pin SMT Socket Outline 1.0 mm	А	July 2008
	Contact Centers		
SO-015	mSATA SSD 0.80 mm Pitch	А	December 2011
SO-016	DDR4 DIMM PTH 284 Pin Socket Outline 0.8 MM	С	August 2014
G Q Q 1 F	Pitch	a	
SO-017	DDR4 DIMM SMT 284 Pin Socket Outline 0.85 MM	С	August 2014
SO 019	PITCH DDP/ and CDDP5M SODIMM 256 Din Socket	C	July 2015
30-018	0 50MM Pitch	C	July 2013
SO-019	DDR4 DIMM Press Fit 284 Pin SO 0 85 Pitch	С	August 2014
SO-021	DDR4 MiniDIMM SMT 288 Pin Socket Outline	A	February 2015
50 021	0 50 mm Pitch		1 coldary 2013
SO-022	12 Pin UFS Socket Outline 0 91 MM Pith (SKT)	А	August 2016
SO-023	DDR5 DIMM SMT Pin Socket Outline 0.85 MM	C	September 2020
50 025	Pitch	C	September 2020
SO-024	262 Pin DDR5 SODIMM, 0.50 mm Pitch Socket	А	April 2019
SO-025	Plastic Dual Connector	A	January 2020
SO-026	Battery Cell R/A T/H Type Connector, 1.2 mm Pitch	A	October 2021
SO-027	Battery Cell Wire Side Connector. 1.2 mm Pitch	A	October 2021
	,	=	

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SO-028	Battery Cell R/A SMT Type Connector, 1.2 mm Pitch	А	October 2021

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T O 1			
TO-1	Metal Can		Archived – JEP 95
TO-2	Metal Can		Archived – JEP 95
TO-3	Diamond Base, .430 Pin Spacing	А	Archived – JEP 95
TO-4 TO-7	MISSING		
TO-5	Axial Leads, .200 Pin Circle	А	Archived - JEP 95
TO-6	Press Fit		Archived – JEP 95
TO-7	Metal Can		Archived – JEP 95
TO-8	Axial Leads, .281 Pin Circle	A	Archived – JEP 95
TO-9	Axial Leads, .200 Pin Circle	А	Archived – JEP 95
TO-10	Stud-Mount, Solid Terminals		Archived – JEP 95
ТО-11	Metal Can with Flange		Archived – JEP 95
TO-12	Axial Leads, .200 Pin Circle	А	Archived – JEP 95
TO-13	Metal Can with Rigid Terminals		Archived – JEP 95
TO-14	Stud-Mount, Rigid Terminals		Archived – JEP 95
TO-15	Stud-Mount, Rigid Terminals		Archived – JEP 95
TO-16	Metal Can with Flange		Archived – JEP 95
TO-17	4 Axial Leads .071 Pin Circle		Archived – JEP 95
TO-18	Axial Leads, .100 Pin Circle	А	Archived – JEP 95
TO-19	MISSING		
TO-20	MISSING		
TO-21	MISSING		
TO-22	Flat Metal Can with Flange		Archived – JEP 95
TO-23	Cylindrical Metal Can with Flange		Archived – JEP 95
TO-24	Cylindrical Metal Can with Flange		Archived – JEP 95
TO-25	Cylindrical Metal Can with Flange		Archived – JEP 95
TO-26	Stud-Mounted Metal Can with Flange		Archived – JEP 95
TO-27	Diamond Flange with Holes and Rigid Leads		Archived – JEP 95
TO-28	Metal Can with Flange		Archived – JEP 95
TO-29	Metal Can with Flange		Archived – JEP 95
TO-30	Metal Can with Flange		Archived – JEP 95
TO-31	Metal Can with Stud Mount		Archived – JEP 95
TO-32	Metal Can with Stud Mount		Archived – JEP 95
TO-33	4 Axial Leads, .200 Pin Circle	А	Archived – JEP 95
TO-34	MISSING		
TO-35	MISSING		
TO-36	Stud-Mount .345 Pin Circle		Archived – JEP 95
TO-37	Diamond Base, .200 Pin Circle	А	Archived – JEP 95
TO-38	Cylindrical Metal Can with Flexible Leads		Archived – JEP 95
TO-39	Axial Leads, .200 Pin Circle	А	Archived – JEP 95
TO-40	Cylindrical Metal Can with Flange and Flexible		Archived – JEP 95
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TO 11			
TO-41	Diamond Base, .430 Pin Circle	A	Archived – JEP 95
TO-42	Axial Leads, .200 Pin Circle	А	Archived – JEP 95
TO-43	Cylindrical Metal Can with Flange and Flexible		Archived – JEP 95
TO 11	Leads		
TO-44	Cylindrical Metal Can with Flange and Flexible		Archived – JEP 95
TO 15	Leads		
TO-45	Cylindrical Metal Can with Flange and Flexible		Archived – JEP 95
T O 14	Leads		
TO-46	Axial Leads, .100 Pin Circle	А	Archived – JEP 95
TO-47	Cylindrical Metal Can with Flange and Flexible		Archived – JEP 95
TO 10	Leads	-	
TO-48	Stud-Mount, Solid Leads	В	Archived – JEP 95
TO-49	Stud-Mount, Braided Terminal	В	Archived – JEP 95
TO-50	Strip Line Package		Archived – JEP 95
TO-51	Strip Line Package		Archived – JEP 95
TO-52	Axial Leads, .100 Pin Circle		Archived – JEP 95
TO-53	Flange-Mount, Rigid Leads		Archived – JEP 95
TO-54	Metal Can with Flange		Archived – JEP 95
TO-55	Metal Can with Flange		Archived – JEP 95
TO-56	Metal Can with Flange		Archived – JEP 95
TO-57	Stud-Mount, Flexible Leads		Archived – JEP 95
TO-58	Metal Can with Flange Mount		Archived – JEP 95
TO-59	Stud-Mount, Solid Terminals		
TO-60	Stud-Mount, Solid Terminals		Archived – JEP 95
TO-61	Stud-Mount, Solid Terminals		Archived – JEP 95
TO-62	Stud-Mount, Solid Terminals		Archived – JEP 95
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TO-64	Stud-Mount, Solid Terminals		Archived – JEP 95
TO-65	Stud-Mount, Solid Terminals		Archived – JEP 95
TO-66	Diamond Base, .200 Pin Spacing	А	Archived – JEP 95
TO-67	Stud-Mount Metal Can with Rigid Leads		Archived – JEP 95
TO-68	Stud-Mount Metal Can with Rigid Leads		Archived – JEP 95
TO-69	Metal Can with Flange, 12 Leads		Archived – JEP 95
TO-70	Metal Can with Flange, 8 Leads		Archived – JEP 95
TO-71	8 Axial Leads .141 Pin Circle		Archived – JEP 95
TO-72	4 Axial Leads, .100 Pin Circle	A	Archived – JEP 95
TO-73	12 Axial Leads, .200 Pin Circle	А	Archived – JEP 95
TO-74	10 Axial Leads, .200 Pin Circle	А	Archived – JEP 95
TO-75	6 Axial Leads, .200 Pin Circle	А	Archived – JEP 95
TO-76	8 Axial Leads, .200 Pin Circle	А	Archived – JEP 95
TO-77	8 Axial Leads, .200 Pin Circle	А	Archived – JEP 95
TO-78	8 Axial Leads, .200 Pin Circle	А	Archived – JEP 95

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TO-79	8 Axial Leads, .200 Pin Circle	А	Archived – JEP 95
TO-80	8 Axial Leads, .200 Pin Circle	А	Archived – JEP 95
TO-81	Stud-Mount Metal Can with Flange		Archived – JEP 95
TO-82	Stud-Mount Metal Can with Flange		Archived – JEP 95
TO-83	Stud-Mount, Double End	В	Archived – JEP 95
TO-84	Multiple-Ended 14-Lead Flatpack	В	Archived – JEP 95
TO-85	Multiple-Ended 14-Lead Flatpack	А	Archived – JEP 95
TO-86	Multiple-Ended 14-Lead Flatpack	А	Archived – JEP 95
TO-87	Double-Ended 14-Lead Flatpack	А	Archived – JEP 95
TO-88	Double-Ended 14-Lead Flatpack	А	Archived – JEP 95
TO-89	Double-Ended 10-Lead Flatpack	В	Archived – JEP 95
TO-90	Double-Ended 10-Lead Flatpack	А	Archived – JEP 95
TO-91	Double-Ended 10-Lead Flatpack	А	Archived – JEP 95
TO-92	Axial Leaded, Flat Index	А	Archived – JEP 95
TO-93	Stud-Mount, Flex Leads	В	Archived – JEP 95
TO-94	Stud-Mount, Flex Leads	В	Archived – JEP 95
TO-95	Double-Ended 14-Lead Flatpack	А	Archived – JEP 95
TO-96	10 Axial Leads, .230 Pin Circle	А	Archived – JEP 95
TO-97	10 Axial Leads, .230 Pin Circle	А	Archived – JEP 95
TO-98	In-Line Axial Leads, Indexed	С	Archived – JEP 95
TO-99	8 Axial Leads, .200 Pin Circle	А	Archived – JEP 95
TO-100	10 Axial Leads, .230 Pin Circle	А	Archived – JEP 95
TO-101	12 Axial Leads, .230 Pin Circle	А	Archived – JEP 95
TO-102	Stud-Mount, Flex Leads		Archived – JEP 95
TO-103	Stud-Mount with Rigid Leads	А	Archived – JEP 95
TO-104	Metal Can with Tab, 4 Leads	А	Archived – JEP 95
TO-105	Epoxy Cylinder with Axial Leads	А	Archived – JEP 95
TO-106	Epoxy Cylinder with Axial Leads	А	Archived – JEP 95
TO-107	Metal Can with Flange, Cylindrical	А	Archived – JEP 95
TO-108	Stud-Mount with Flexible Terminals	А	Archived – JEP 95
TO-109	Flange-Mount with Terminals	А	Archived – JEP 95
TO-110	Epoxy with Axial Leads, 10 Leads	А	Archived – JEP 95
TO-111	Stud-Mount, Solid Leads	А	Archived – JEP 95
TO-112	Metal Can with Flange	А	Archived – JEP 95
TO-113	Strip Line with Metal Can	A	Archived – JEP 95
TO-114	Stud-Mount, 4 Solid Terminals	A	Archived – JEP 95
TO-115	Stud-Mount with Rigid Leads	А	Archived – JEP 95
TO-116	DIP, .300 Wide	А	Archived – JEP 95
TO-117	Lateral, 4 Flat Leads	А	Archived – JEP 95
TO-118	Stud-Mount, Flex Leads	А	Archived – JEP 95
TO-119	Strip Line Package, 3 Leads	А	Archived – JEP 95
ТО-120	Strip Line Package, 4 Leads	А	Archived – JEP 95

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то-121	Cylindrical Metal Can with Perpendicular Leads	А	Archived – IEP 95
TO-121 TO-122	Leadless Inverted Device	A	Archived – IEP 95
TO-122 TO-123	Diamond Base 200 Pin Circle	A	Archived – IEP 95
TO-125 TO-124	Diamond Base, 200 Pin Circle	A	Archived – IEP 95
TO-121 TO-125	Metal Can with Flange	A	Archived – IEP 95
TO-125 TO-126	Flat Lead 090 Pin Spacing	A	Archived – IEP 95
TO-127	Flat Lead 166 Pin Spacing	A	Archived – JEP 95
TO-128	Stud-Mount Lateral 4 Flat Leads	A	Archived – IEP 95
TO-129	Stud-Mount, Lateral 4 Flat Leads	A	Archived – IEP 95
TO-130	Strip Line Package 4 Leads	A	Archived – IEP 95
TO-131	Strip Line Package, 4 Leads	A	Archived – IEP 95
TO-132	Stud-Mount with Flexible Leads	A	Archived – IEP 95
TO-200 AA-AD	Disc Type Family	I	April 1984
TO-200 AE-AE	Disc Type Family	I	July 1985
TO-2007112711	Coaxial Family	B	Archived $-$ IEP 95
TO-202	Tab-Mounted Peripheral Leads	F	February 1978
TO-202	Press-Fit Family - Solid Leads	Ċ	Archived $-$ IEP 95
TO-204 AA-AE	Flange-Mounted Header Family 430) Pin Spacing	Č	November 1982
TO-205	Header Type 200 Pin Circle	Ē	November 1982
TO-206	Header Type .100 Pin Circle	B	November 1982
TO-207	Stud-Header Family, .690 Pin Circle	Ă	Archived – JEP 95
TO-208 AA-AD	Stud Hex Base Family (Solid Terminals)	A	June 1974
TO-208 AE-AG	Stud Hex Base Family (Solid Terminals)	Ċ	May 1979
TO-209	Stud-Hex. Flexible Terminals	Ă	June 1974
TO-210 AA-AE	Stud-Hex Base Family (Solid Terminals)	A	Archived – JEP 95
TO-211 MA-MB	Stud-Hex Base Family (Solid Leads)	A	Archived – JEP 95
TO-212 MA	Stud-Hex Base Family (Solid Leads)	A	Archived – JEP 95
TO-213	Flange-Mounted Header200 Spacing	A	September 1976
TO-214	Stud-Hex Base Family (Solid Leads)	А	Archived – JEP 95
TO-215	Coaxial Type	A	June 1971
TO-216	Stud-Mounted Stripline	А	June 1971
TO-217	Stud Rectangular Base Family	А	Archived – JEP 95
TO-218	Flange-Mounted Header	Е	June 1986
TO-219	Flange-Mounted Header	В	December 1977
TO-220	Plastic Multi Position Flange Mount Mixed	L.01	December 2020
	Technology 0.10 in Pitch Package		
TO-221 AA-AB	Flat-Mounted Peripheral Leads	А	Archived – JEP 95
TO-222 AA-AB	Header Family (.200 Pin Circle)	A	Archived – JEP 95
TO-223 AA-AB	Header Family (.100 Pin Circle)	A	Archived – JEP 95
TO-224 AA	Disc Family - Peripheral Leads	Ā	Archived – JEP 95
TO-225	Flat Mounted Family (Peripheral Terminals)	C	Archived – JEP 95
TO-226 AE	Header Family, Flat Index	A	December 1981

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	Diag Family Darinkaral Lands	٨	Anabiana d IED 05
TO-227 AA-AC	Stud Mounted Family (Derinheral Terminals)	A	Archived JEP 95
TO-228 AA-AC	Stud-Wounted Family (Peripheral Terminals)	A	Archived JEP 95
TO 220 A A AD	Sulpine Reader Failing	A	Archived JEP 95
TO 221 AA AD	Stud Hay Daga Family (100 % 200 Din Circle)	D A	Archived JEP 95
TO 222 AA AC	Stud Hex-Dase Failing (.100 & .200 Fill Clicle)	A	Archived JEP 95
TO-232 AA-AC	Stud Mounted Radial Lead Failing	A	Archived JEP 95
TO 224 AAAD	Dediel Lead Femily	A	Archived JEP 95
TO-254 AA-AD	Raulai Leau Failily	A	Archived – JEP 95
TO-235	Plastic Small Outline Deckage (SOT/SOD), 2 Loade	A	Archived – JEP 95
TO-230	Hastic Small Outline Package (SOT/SOP), 5 Leads	П	January 1999
TO-237	Flange Mounted Header Destangular	В	October 1979 March 1092
TO 220 A A AD	Flange-Mounted Header, Rectangular	D	March 1982
10-239 AA-AB	.490 Pin Circle	В	Archived – JEP 95
TO-240	Terminal Strip Power Module	В	March 1981
TO-241	Header Family(.100 Pin Circle)	А	Archived – JEP 95
TO-242	Header Family Flange Mounted (.100 Pin Circle)	А	Archived – JEP 95
TO-243	Header Family, Peripheral Terminal	С	July 1986
TO-244	Flange-Mounted Rectangular Base	В	September 1984
TO-245	Header Family, .100 Pin Circle DRAWING NOT AV	VAILABLE	
TO-246	Header Family, .200 Pin Circle DRAWING NOT AV	VAILABLE	
TO-247	Flange-Mounted Header Family	Е	June 2004
TO-248	Power Module	А	Archived – JEP 95
TO-249	Flange Mounted Family (Rectangular Base)	В	Archived – JEP 95
TO-250	4-Lead DIP .300" Spacing	А	July 1985
TO-251	Header Family, Peripheral Terminals	D	June 2002
TO-252	Flange Mounted Family Surface Mount	F	January 2017
TO-253	Plastic Small Outline Package (SOT/SOP), 4 Leads	D	January 1999
TO-254	Flange-Mounted, Peripheral Leads	А	November 1986
TO-255	Disc Family, Peripheral Leads Not Published		December 1987
TO-256	Flat Mounted Transistor	А	March 1988
TO-257	Flange Mounted Header Family (Peripheral	С	September 1996
	Terminals)		
TO-258	Flange-Mounted 5.08 Spacing	А	February 1988
TO-259	Flange-Mounted Header Family	В	April 1991
TO-260	Ceramic Header Axial 3-Lead	А	April 1989
TO-261	Plastic Small Outline Package SOP/SOT	С	May 2002
TO-262	Flange-Mounted Header Family	А	June 1990
TO-263	Plastic Surface Mounted Header Family	F	September 2013
TO-264	Header Family Insertion Mount (Peripheral Terminals)	В	November 1993
TO-265	3 Lead Flange Mounted Ceramic Power Package	А	June 1993

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TO-266	Opto Family Insertion Mount (Peripheral Terminals)	А	April 1994
TO-267	Hermetic Flange Mounted Header Family	А	September 1994
	(Peripheral Terminals) Three Lead, 5.0 Spacing		
TO-268	Header Family Surface Mounted (Peripheral	А	June 1995
	Terminals)		
TO-269	Small Outline Surface Mount (R-PDSO-G4)	А	August 1996
TO-270	Two Lead Surface Mount Power Package	С	July 2008
TO-271	Quad Flat Pack Surface Mount Thermally Enhanced	А	May 1998
TO-272	6-Lead Screw Mount Power Package	В	February 2004
TO-273	Plastic Flange Mounted Package, 3 Leads	В	July 2003
TO-274	Plastic Clip Mounted Package, 3 Leads	А	March 2000
TO-275	Plastic Flange Mounted Power Package, 2 Leads	А	November 2000
TO-276	Ceramic No Lead Chip Carrier	А	January 2001
TO-277	Small Outlines Plastic Surface Mount Package	А	January 2006
TO-278	Thin Profile, 3 Lead Plastic Small Outline Surface	В	November 2006
	Mount		
TO-279	Plastic Surface Mounted Header Family	В	August 2008
TO-280	Flange Mounted Header Family	А	August 2010
TO-281	Fully Molded Flange Header Family Full-Pak	А	November 2011

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UO-005	22 Beam Chip	В	Archived – JEP 95
UO-006	24 Beam Chip	В	Archived – JEP 95
UO-007	26 Beam Chip	В	Archived – JEP 95
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UO-015	4 Beam Chip	В	Archived – JEP 95
UO-016	34 Beam Chip	А	Archived – JEP 95
UO-017	Tape Automated Bonding Uncased Outline	А	October 1988
UO-018	Tape Automated Bonding (TAB) Package Family	В	July 1993